

CLAIMS

WHAT IS CLAIMED IS:

1. A semiconductor device, comprising:
 - a plurality of leads; and
 - a resin encapsulated body comprising
 - a first surface;
 - a second surface; and
 - four side surfaces, wherein said leads project outward from the resin encapsulated body through at least one of said four side surfaces, wherein said leads project through the second surface, further wherein said leads project outward such that at least one side of the projecting lead shows itself.
2. The semiconductor device of Claim 1, wherein said second surface has a smaller area than said first surface.
3. The semiconductor device of Claim 1, further comprising:
 - a plurality of hang leads.
4. The semiconductor device of Claim 2, further comprising:
 - a plurality of hang leads.

5. The semiconductor device of Claim 1, wherein an outside projecting end of said leads is coated with metal.

6. The semiconductor device of Claim 5, wherein said leads are coated with metal by a plating process.

7. The semiconductor device of Claim 3, wherein there are two hang leads.

8. The semiconductor device of Claim 4, wherein there are two hang leads.

9. The semiconductor device of Claim 1, wherein the resin encapsulated body contains a tab sealed therein.

10. The semiconductor device of Claim 3, wherein the resin encapsulated body contains a tab sealed therein.

11. The semiconductor device of Claim 5, wherein the resin encapsulated body contains a tab sealed therein.

12. The semiconductor device of Claim 7, wherein the resin encapsulated body contains a tab sealed therein.

13. A method for manufacturing a semiconductor device having a resin encapsulated body and a plurality of leads which extend into at least one surface of said resin encapsulated body, comprising the steps of:

interposing members between said plurality of leads to prevent resin flow between said leads;

performing resin molding; and

separating said interposed members from said leads.

14. The method of Claim 13, further comprising the step of:

cutting off the ends of said leads.

15. The method of Claim 13, further comprising the step of:

coating said leads with a metal layer.

16. The method of Claim 15, further comprising the step of:

inserting plating holes into said plurality of leads prior to said coating step.

17. The method of Claim 13, wherein said members are push-back members.

18. A semiconductor device, comprising:

a resin encapsulated body including a top surface, a bottom surface, and four side surfaces; and

a plurality of leads extending outward from the resin encapsulated body through at least one of said four side surfaces and through said second surface, wherein each of said plurality of leads includes an extending end surface and two extending side surfaces which are free from resin.

19. The semiconductor device of Claim 18, wherein said extending side surfaces and said extending end surface are coated with metal.

20. The semiconductor device of Claim 18, further comprising:

a plurality of hang leads.